

L Number	Hits	Search Text	DB	Time stamp
1	81068	(laminate laminted laminating lamination) with (substrate carrier board pcb cb pb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 14:46
2	229380	antenna	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 14:46
3	88203	wire and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 14:51
4	155	((laminate laminted laminating lamination) with (substrate carrier board pcb cb pb)) and antenna and (wire and pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 14:52